

Title (en)  
Process for manufacturing thick film varistors.

Title (de)  
Verfahren zur Herstellung von Dickfilm-Varistoren.

Title (fr)  
Procédé de fabrication de varistances à film épais.

Publication  
**EP 0000864 A1 19790307 (DE)**

Application  
**EP 78100192 A 19780619**

Priority  
DE 2735484 A 19770805

Abstract (en)  
[origin: US4186367A] A glass-free thick film varistor operable at operating voltages ranging from about 30 to 200 volts per mm of active varistor material is produced by providing a screen-printable paste comprised of a non-glass containing substantially homogeneous mixture of granular varistor materials which have ZnO as the main component thereof and an organic binder, applying such paste in a desired pattern onto an insulating substrate and sintering such applied paste at relatively high temperatures so as to convert the paste into thick film varistors.

Abstract (de)  
Zur Herstellung von Dickfilm-Varistoren mit Zinkoxid als Hauptkomponente wird aus den Varistormaterialien und einem Bindemittel eine siebdruckfähige Varistorpaste hergestellt, die anschliessend auf ein isolierendes Substrat aufgebracht und gesintert wird. Gemäss der Erfindung wird eine glasfreie Varistorpaste verwendet, welche lediglich ein organisches Bindemittel, aber keine Glasfritte enthält.

IPC 1-7  
**H01C 7/10**; C04B 35/00; H01C 17/06

IPC 8 full level  
**H01C 7/10** (2006.01); **H01C 17/065** (2006.01)

CPC (source: EP US)  
**H01C 7/1006** (2013.01 - EP US); **H01C 17/06546** (2013.01 - EP US); **Y10T 29/49082** (2015.01 - EP US)

Citation (search report)  
[A] DE 2446708 A1 19760408 - SIEMENS AG

Cited by  
US5973588A; US5837178A; EP0141179A3; EP0126984A1; FR2545259A1; GB2242065A; FR2659785A1; GB2242065B; US6183685B1; US6334964B1; US6743381B2

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**EP 78100192 A 19780619**; CA 308575 A 19780802; DE 2735484 A 19770805; IT 2649278 A 19780804; JP 9445278 A 19780802; US 91785778 A 19780622